| L Number | Hits | Search Text | DB | Time stamp |
|-------------|------|--|--------------------|---------------------|
| 9 | 506 | ((gray grey) same imag\$3) same (ic semiconduct\$ wafer (integrat\$ near | USPAT | 2004/07/14 17:09 |
| | | circuit\$)) | | |
| 10 | 623 | (382/141).CCLS. | USPAT; US-PGPUB | 2004/07/14 |
| 11 | 744 | ((gray grey) same imag\$3) same (ic | USPAT; | 2004/07/14 |
| | | <pre>semiconduct\$ wafer (integrat\$ near circuit\$))</pre> | US-PGPUB | 17:38 |
| 12 | 10 | ((382/141).CCLS.) and (((gray grey) same | USPAT; | 2004/07/14 |
| | | imag\$3) same (ic semiconduct\$ wafer | US-PGPUB | 17:10 |
| 13 | 2527 | (integrat\$ near circuit\$))) (356/600,601,625,390,448,237.1,237.2).CCLs | .USPAT; | 2004/07/14 |
| | | | US-PGPUB | 17:10 |
| 14 | 316 | (348/125,86).CCLS. | USPAT; US-PGPUB | 2004/07/14 |
| 15 | 201 | (250/559.34,550.29,559.19).CCLS. | USPAT; | 2004/07/14 |
| 16 | 855 | (29/740).CCLS. | US-PGPUB USPAT; | 17:11 2004/07/14 |
| | | (25) 140) . CCID. | US-PGPUB | 17:11 |
| 17 | 566 | (73/104).CCLS. | USPAT; US-PGPUB | 2004/07/14 17:11 |
| 18 | 13 | (((gray grey) same imag\$3) same (ic | USPAT | 2004/07/14 |
| | | semiconduct\$ wafer (integrat\$ near | | 17:33 |
| | | circuit\$))) and ((356/600,601,625,390,448,237.1,237.2).CCL | 5.) | |
| 19 | 2 | 6088108.URPN. | USPAT | 2004/07/14 |
| 20 | 5 | ("4553843" "5311304" "5528371" | USPAT | 17:13 2004/07/14 |
| 20 | J | "5663799" "5909285").PN. | USERI | 17:13 |
| 21 | 7 | 5909285.URPN. | USPAT | 2004/07/14 17:15 |
| 22 | 3 | 6141040.URPN. | USPAT | 2004/07/14 |
| | 10 | 5500071 (1777) | 110 D B W | 17:16 |
| 23 | 10 | 5528371.URPN. | USPAT | 2004/07/14 |
| 24 | 7 | (((gray grey) same imag\$3) same (ic | USPAT; | 2004/07/14 |
| - | | <pre>semiconduct\$ wafer (integrat\$ near circuit\$))) and ((348/125,86).CCLS.)</pre> | US-PGPUB | 17:34 |
| 25 | 1 | (((gray grey) same imag\$3) same (ic | USPAT; | 2004/07/14 |
| | | <pre>semiconduct\$ wafer (integrat\$ near circuit\$))) and</pre> | US-PGPUB | 17:34 |
| | | ((250/559.34,550.29,559.19).CCLS.) | | |
| 26 | 0 | <pre>(((gray grey) same imag\$3) same (ic semiconduct\$ wafer (integrat\$ near</pre> | USPAT; US-PGPUB | 2004/07/14 17:34 |
| | | circuit\$))) and ((29/740).CCLS.) | OS FGFOD | 17.54 |
| 27 | 0 | (((gray grey) same imag\$3) same (ic | USPAT; | 2004/07/14 17:34 |
| | | semiconduct\$ wafer (integrat\$ near circuit\$))) and ((73/104).CCLS.) | US-PGPUB | 11.34 |
| 28 | 846 | ((pixel\$ same intensit\$) same imag\$3) | USPAT; | 2004/07/14 17:39 |
| | | same (ic semiconduct\$ wafer (integrat\$ -near-circuit\$)- | US-PGPUB | 11:39 |
| 29 | 801 | ((gray grey) same imag\$3) same (ic | USPAT; | 2004/07/14 |
| | | <pre>semiconduct\$ wafer (integrat\$ near circuit\$))</pre> | US-PGPUB | 17:36 |
| 30 | 57 | (((gray grey) same imag\$3) same (ic | USPAT; | 2004/07/14 |
| | | <pre>semiconduct\$ wafer (integrat\$ near circuit\$))) not (((gray grey) same</pre> | US-PGPUB | 17:36 |
| | | imag\$3) same (ic semiconduct\$ wafer | | |
| 31 | 0 | <pre>(integrat\$ near circuit\$))) ((((gray grey) same imag\$3) same (ic</pre> | USPAT; | 2004/07/14 |
| | | semiconduct\$ wafer (integrat\$ near | US-PGPUB | 17:37 |
| | | circuit\$))) not (((gray grey) same imag\$3) same (ic semiconduct\$ wafer | | |
| | | (integrat\$ near circuit\$)))) and | | |
| | | (((356/600,601,625,390,448,237.1,237.2).cc | LS.) | |
| | | ((348/125,86).CCLS.) ((250/559.34,550.29,559.19).CCLS.) | | |
| | | ((29/740).CCLS.) ((73/104).CCLS.)) | | |

| 32 | 28 | (((gray grey) same imag\$3) same (ic | USPAT; | 2004/07/14 |
|----|-----|--|-----------|------------|
| | | semiconduct\$ wafer (integrat\$ near | US-PGPUB | 17:37 |
| | | circuit\$))) and | | l |
| | | (((356/600,601,625,390,448,237.1,237.2).cc | Ls.) | |
| | | ((348/125,86).CCLS.) | | |
| | | ((250/559.34,550.29,559.19).CCLS.) |] | |
| | | ((29/740).CCLS.) ((73/104).CCLS.)) | | |
| 33 | 123 | ((gray grey) same imag\$3) same (ic | EPO; JPO; | 2004/07/14 |
| | | semiconduct\$ wafer (integrat\$ near | DERWENT; | 17:39 |
| | | circuit\$)) | IBM TDB | |
| 34 | 66 | ((pixel\$ same intensit\$) same imag\$3) | EPO; JPO; | 2004/07/14 |
| | | same (ic semiconduct\$ wafer (integrat\$ | DERWENT; | 17:39 |
| | | near circuit\$)) | IBM TDB | 1 |